SPECIFICATION

REFOND P/N

RF-OMRA30TS-BM-G

Mass Production

Contents

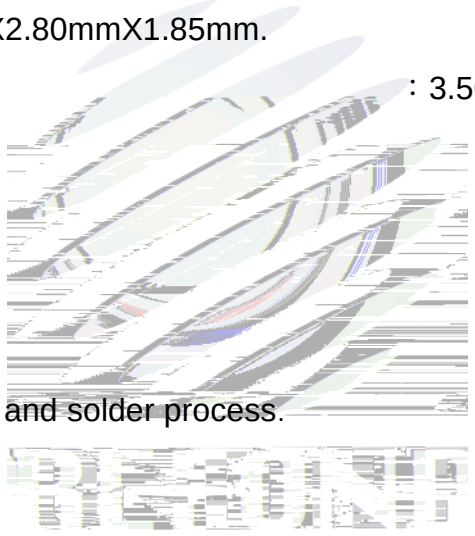
1. Description

1.1

The source color devices are made with AlGaInp on Substrate Light Emitting Diode .

Product Package:3.50mmX2.80mmX1.85mm.

：3.50mmX2.80mmX1.85mm。



1.2Features

PLCC4 Package.

Extremely wide viewing angle.

Suitable for all SMT assembly and solder process.

Available on tape and reel.

Moisture sensitivity level: Level 2.

1.4Package Dimension

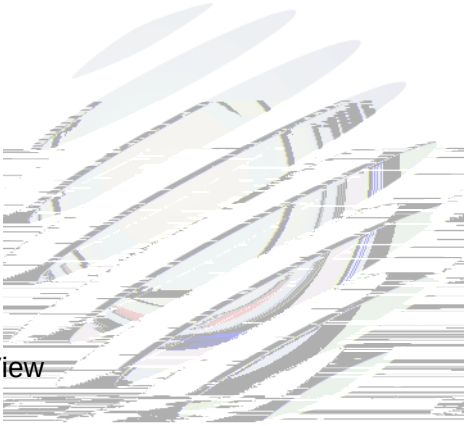


Fig.1-3BottomView

Fig.1-4Polarity

Fig.1-5Soldering Patterns

Notes

All dimensions units are millimeters.

1.5Product Parameters

Table 1-1 Electrical / Optical Characteristics at Ts=25°C

Item	Symbol	Test Condition	Value			Unit
			Min.	Typ.	Max.	
Forward Voltage	V_F	I_F=50mA	1.8	2.2	2.4	V
Reverse Current	I_R	V_R=5V	---	---	10	uA
Luminous Intensity	IV	I_F=50mA	1800	2900	3500	mcd
Dominant wavelength	Wd	IF=50mA	610	615	620	nm
Viewing Angle		I_F=50mA	---	120	---	deg
Thermal Resistance.	R_{THJ-S}	I_F=50mA	---	---	130	/W

Table 1-2 Absolute Maximum Ratings at Ts=25°C

Parameter	Symbol	Rating	Units
Power Dissipation	P_D	168	mW
Forward Current	I_F	70	mA
Peak Forward Current	I_{FP}	100	mA
Reverse Voltage	V_R	5	V
Electrostatic Discharge (HBM)	E_{SD}	2000	V
Operating Temperature	T_{OPR}	-40 ~ +100	
Storage Temperature	T_{OPR}	-40 ~ +100	
Junction Temperature	T_J	120	

Notes

1. 1/10 Duty cycle, 10ms pulse width.

2. The above forward voltage measurement allowance tolerance is ±0.1V.

3. The above color coordinates measurement allowance tolerance is ±0.005. ±

4. The above luminous intensity measurement allowance tolerance ±10%.

5. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.

6. All measurements were made under the standardized environment of Refond.

7.When the LEDs are in operation the maximum current should be decided after measuring the package temperature, junction temperature should not exceed the maximum rate

8. ESD yield is over 90% at 2000V ESD (HBM). ESD protection during products handing is needed.

1.6Bin Range Of Forward Voltage and Luminous Intensity and Dominant wavelength (IF=50mA) BIN (IF=50mA)

Table 1-3

V_F V	B1	B2	C1	C2	D1	D2
	1.8-1.9	1.9-2.0	2.0-2.1	2.1-2.2	2.2-2.3	2.3-2.4
IV mcd	N1	N2	O1			
	1800-2300	2300-2800	2800-3500			
WD(nm)	C1	C2	D1	D2		
	610-612.5	612.5-615	615-617.5	617.5-620		

1.7 Typical Optical Characteristics Curves

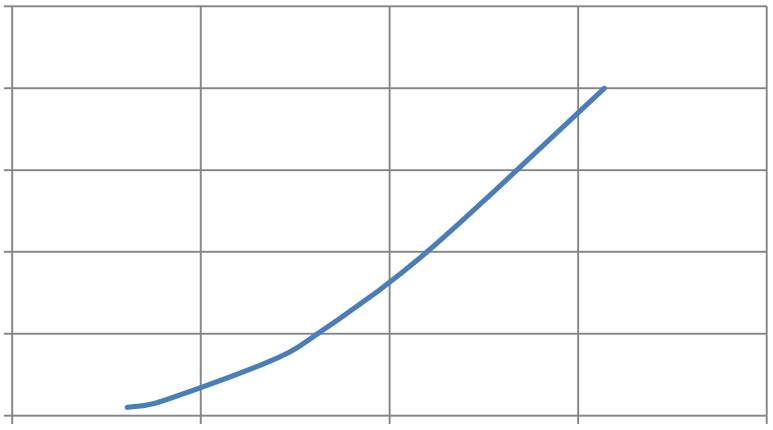


Fig. 1-7 Forward Voltage Vs Forward Current

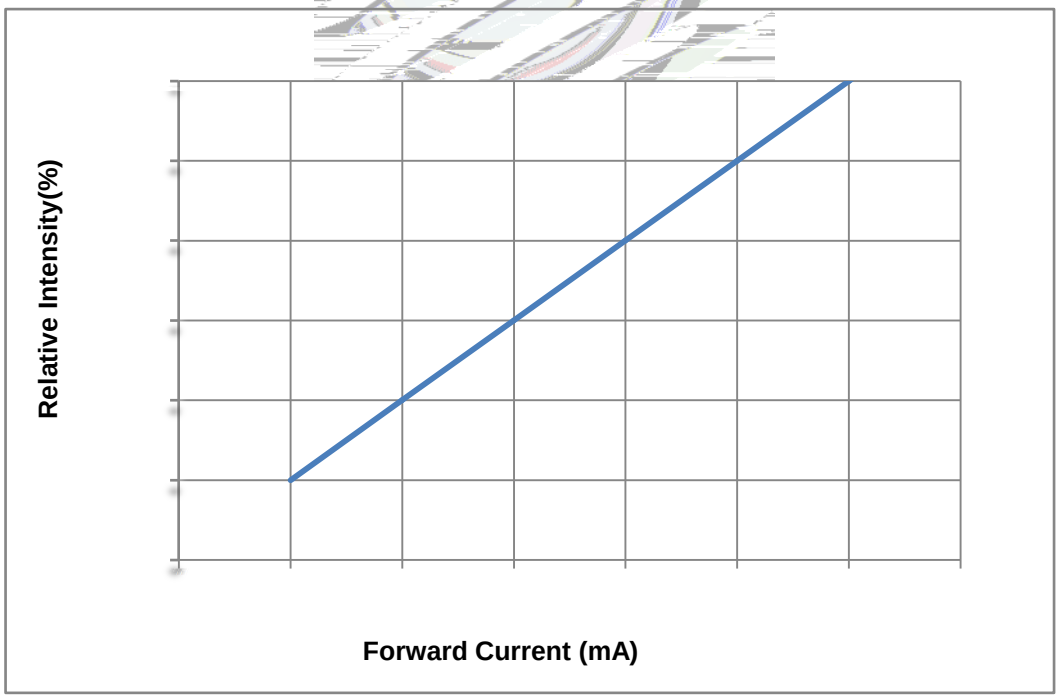


Fig. 1-8 Forward Current Vs Relative Intensity

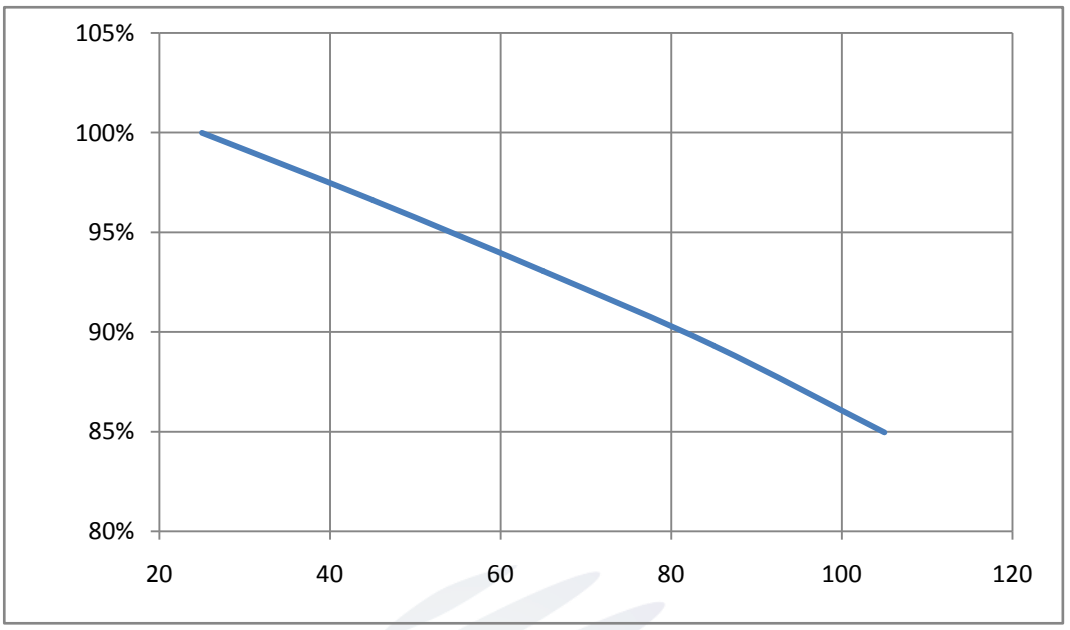


Fig. 1-9 Solder Temperature Vs Relative Intensity

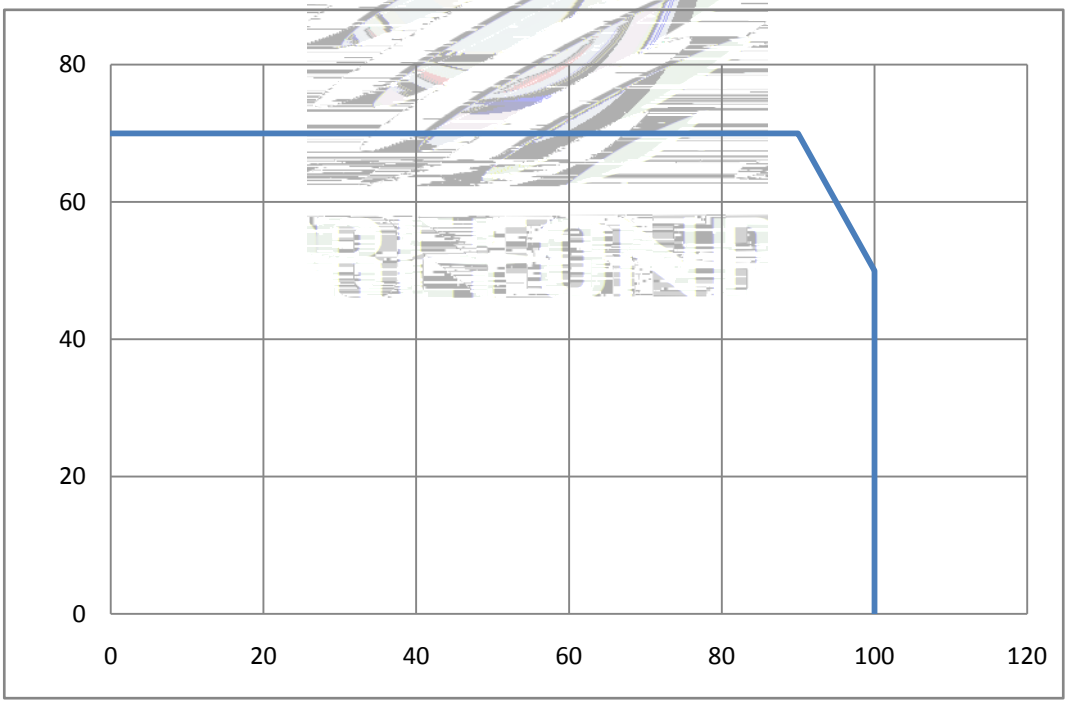


Fig. 1-10 Solder Temperature Vs Forward Current

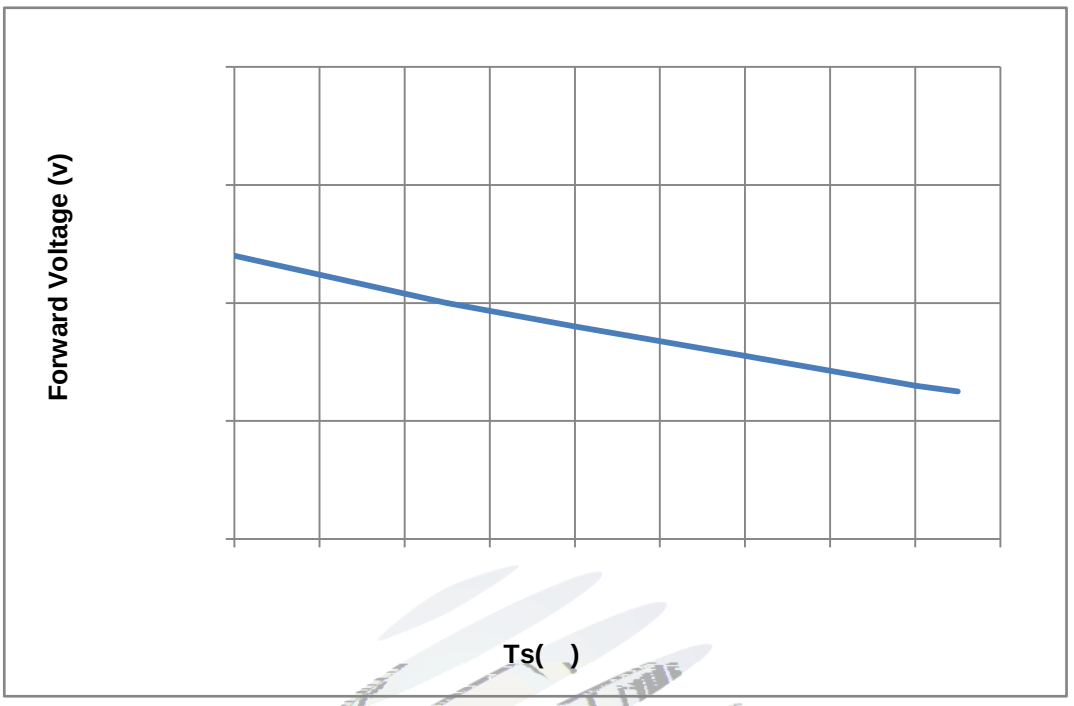


Fig. 1-11 Forward Voltage Vs Solder Temperature

Fig. 1-12 Radiation diagram

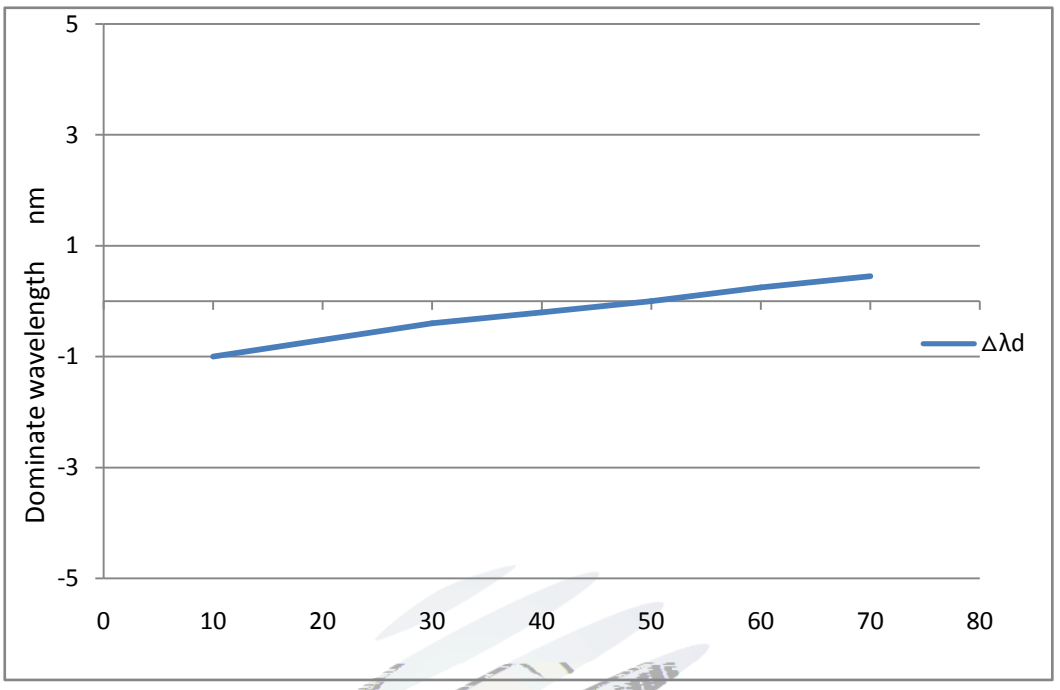


Fig. 1-13 Forward current vs. Dominate wavelength (Ts=25°C)

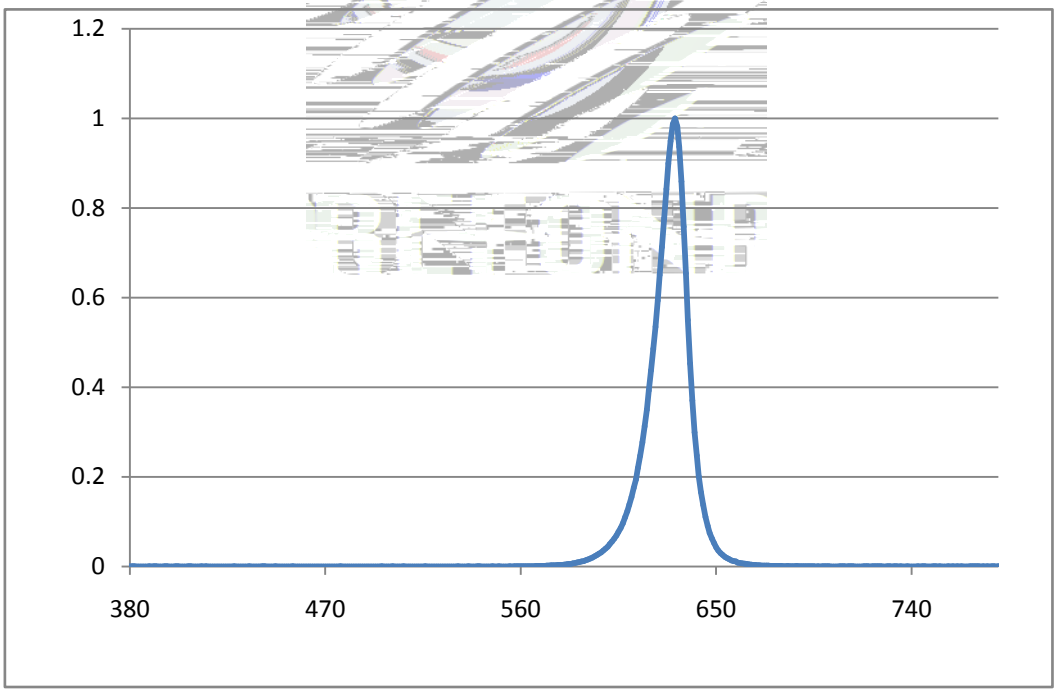


Fig. 1-14 Spectrum Distribution

2. Packaging

2.1 Packaging Specification

Package:2000pcs/reel. 2000pcs

2.1.1

2.1.3Label Form Specification

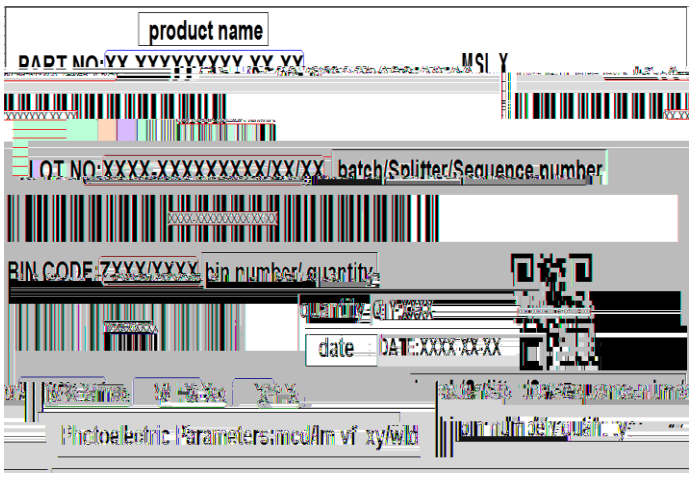


Fig. 2-3 Label

	Specification
PART NO.	Part Number
SPEC NO.	Spec Number
LOT NO.	Lot Number
BIN CODE	Bin Code
	Luminous flux
XY	Chromaticity Bin
V_F	Forward Voltage
WLD	Wavelength
QTY	Packing Quantity
DATE	Made Date

2.2Moisture Resistant Packing

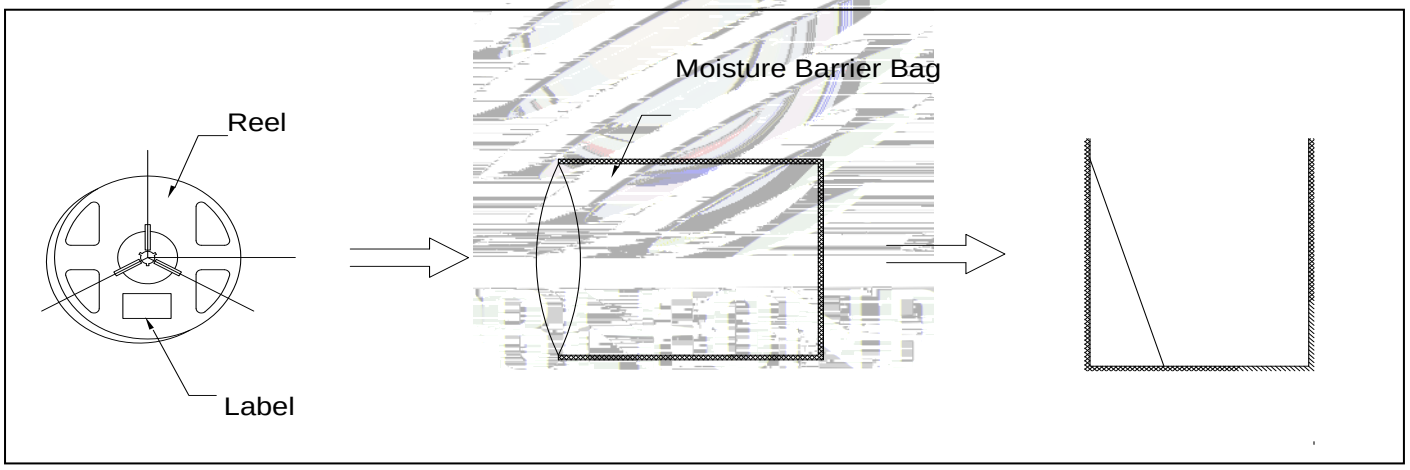


Fig.2-4Moisture Resistant Packing

High Temperature High Humidity Life Test	JESD22-A101	85 / 85%R_H I_F=50mA	1000hrs.	20pcs.	0/1
Temperature Humidity Storage	JEITA ED-4701 100 103	T_A=85 R_H=85%	1000hrs.	20pcs.	0/1

2.5 Criteria For Judging Damage

Table 2-4**Criteria For Judging Damage**

Test Items	Symbol	Test Condition	Criteria For Judgement	
			Min.	Max.
Forward Voltage	V_F	I_F=50mA	-	U.S.L*)x1.1
Reverse Current	I_R	V_R = 5V	-	U.S.L*)x2.0
Luminous Flux		I_F=50mA	L.S.L*)x0.7	-

Notes

1.U.S.L: Upper standard level L.S.L: Lower standard level

2.The above reliability tests is based on the verification of a single/strip LED of Refond's existing experimental platform,the reliability experiment was taken under good heat dissipation conditions. when customers applies the LED to the series and parallel circuit, should take consideration of all the factors such as the current, voltage distribution, heat dissipation and others.

3.The technical information shown in the data sheets is limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license.

3. SMT Reflow Soldering Instructions SMT

3.1SMT Reflow Soldering Instructions SMT

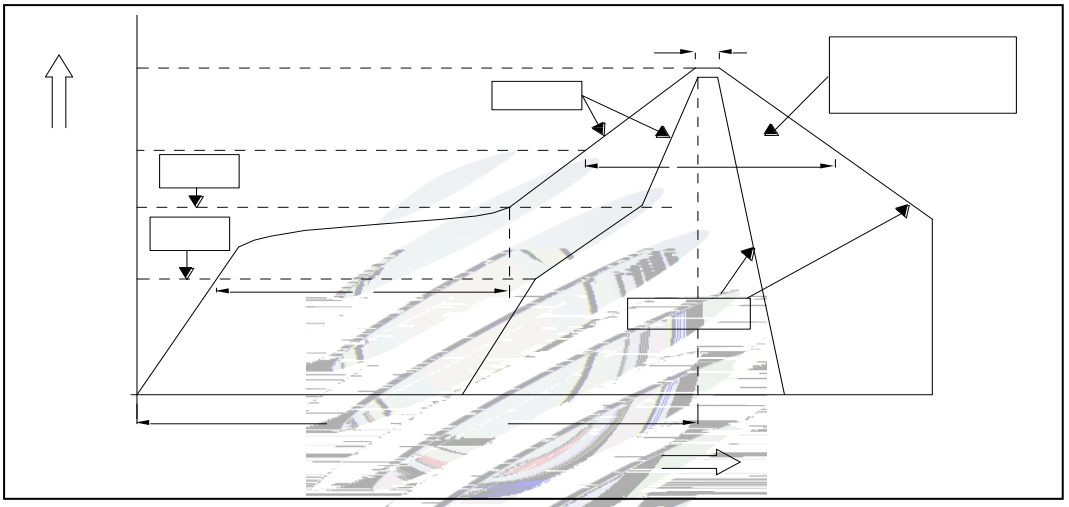


Fig.3-1SMT Reflow Soldering Instructions SMT

Table 3-1Reflow parameters

Average temperature rise speed Tsmax T_P	3 °C/ Max 3 °C/ s
Preheating: minimum temperature (Tsmin)	150 °C
Preheating: Max temperature (Tsmax)	200 °C
Preheating: Time Tsmin Tsmax	60 - 120 60s-120s
Time limited to maintain high temperature: the temperature (T_L)	217 °C
Time limited to maintain high temperature: The Time (t_L)	60 Max 60s
Peak /Classification of temperature: / (T_P)	260 °C
Time limit classification of peak temperature time t_p	10 Max 10s

(TP) 5 °C Hold time within 5 C with the actual peak temperature (TP)	30 Max 30s
Cooling speed	6 °C/ Max 6 °C/ s
25 °C Needed time from 25 °C to Tp	8 Max 8 minutes

Notes

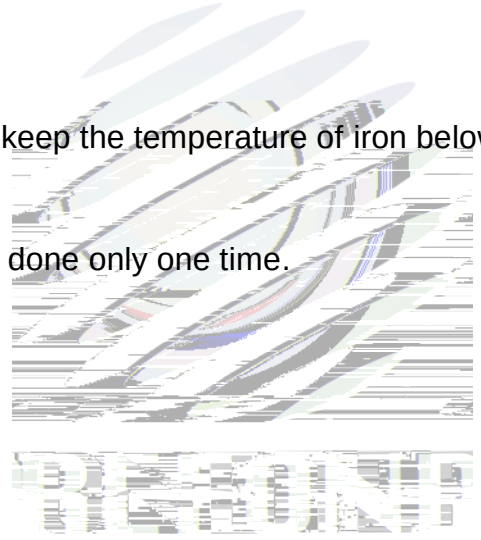
(1)Reflow soldering should not be done more than twice. If more than 24 hours between the two solderings ,LED will be damaged.

(2)When soldering , do not put stress on the LEDs during heating.

3.1.1 Soldering Iron

(1) When do soldering by hand, keep the temperature of iron below less 300℃ less than 3 seconds

(2) Soldering by hand should be done only one time.



(2) Components should not be mounted on warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board.LED

(3) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.

4. Handling Precautions

4.1 Handling Precautions

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement.LED

(2) In order to prevent ex-ternal material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM,the single content of Chlorine elementis required to be less than 900PPM,the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement.

(3) VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected to be used in the construction of fixtures can help prevent these issues. Refond advises against the use of any chemicals or materials that have been found or are suspected to have an adverse affect on device performance or reliability. To verify

compatibility, Refond recommends that all chemicals and materials be tested in the specific application and environment for which they are intended to be used. Attaching LEDs, do not use adhesives that outgas organic vapor.

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust,requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED.

(9)Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS).

(10) Other points for attention, please refer to our relevant information.

Version History/

Date	Revisor	Version	Verifier	Remarks
2021/3/13		E0		

www.refond.com

Declare

This specification is written both in English and in Chinese and the latter is formal.